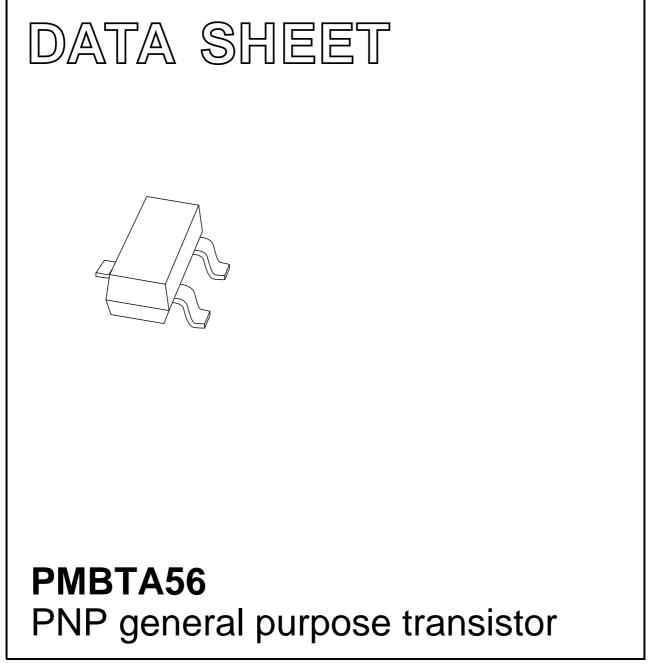
# DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 1999 Apr 09 2004 Jan 09



## Product data sheet

# PNP general purpose transistor

### FEATURES

- High current (max. 500 mA)
- Low voltage (max. 80 V).

## APPLICATIONS

• General purpose switching and amplification, e.g. telephony and professional communication equipment.

## DESCRIPTION

PNP transistor in a SOT23 plastic package. NPN complement: PMBTA06.

#### MARKING

TYPE NUMBER	MARKING CODE <sup>(1)</sup>
PMBTA56	*2G

## Note

1. \* = p : Made in Hong Kong.

\* = t : Made in Malaysia.

\* = W : Made in China.

#### **ORDERING INFORMATION**

TYPE		PACKAGE		
NUMBER	NAME	DESCRIPTION	VERSION	
PMBTA56	_	plastic surface mounted package; 3 leads	SOT23	

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	-80	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	-80	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	-5	V
I <sub>C</sub>	collector current (DC)		-	-500	mA
I <sub>CM</sub>	peak collector current		-	-1	А
I <sub>BM</sub>	peak base current		-	-200	mA
P <sub>tot</sub>	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$ ; note 1	-	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

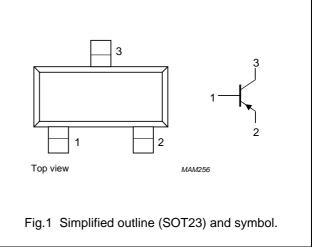
#### Note

1. Transistor mounted on an FR4 printed-circuit board.

## PMBTA56

#### PINNING

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	



# PNP general purpose transistor

# PMBTA56

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1	500	K/W

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

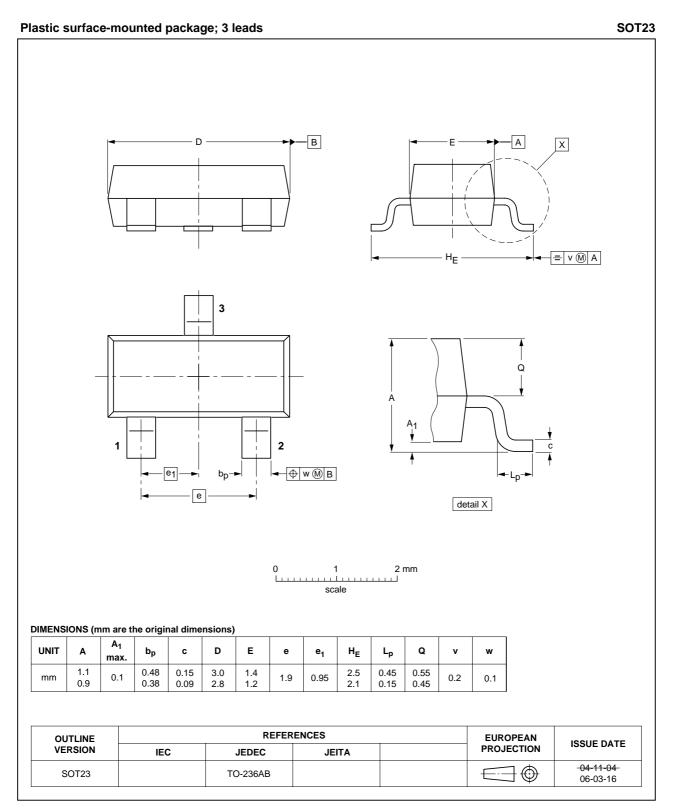
## **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	$I_E = 0; V_{CB} = -80 V$	-	-50	nA
I <sub>EBO</sub>	emitter cut-off current	$I_{C} = 0; V_{EB} = -5 V$	-	-50	nA
h <sub>FE</sub>	DC current gain	$I_{C} = -10 \text{ mA}; V_{CE} = -1 \text{ V}$	100	-	
		$I_{C} = -100 \text{ mA}; V_{CE} = -1 \text{ V}$	100	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_{C} = -100 \text{ mA}; I_{B} = -10 \text{ mA}$	-	-250	mV
V <sub>BE</sub>	base-emitter voltage	$I_{C} = -100 \text{ mA}; V_{CE} = -1 \text{ V}$	-	-1.2	V
f⊤	transition frequency	$I_{C} = -100 \text{ mA}; V_{CE} = -1 \text{ V};$ f = 100 MHz	50	-	MHz

# PNP general purpose transistor

## PACKAGE OUTLINE



# PMBTA56

# PNP general purpose transistor

PMBTA56

#### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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# **NXP Semiconductors**

#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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